

Product / Package Information

Package	LFCSP - Sawn
Body Size (mm)	4 X 4 X 0.75 (2.1 EP)
Lead Count	24
Terminal Finish	100 Sn

Environmental Information

RoHS Compliant	Yes
High Temperature Compliant	Yes
Halogen Free Compliant	Yes
REACH SVHC Compliant	Yes

Materials Declaration

Molding Compound

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Silica	60676-86-0	2.22E-02	86.2	862000	44.71	447068
Thermosets	Epoxy resin	Proprietary	1.55E-03	6.0	60000	3.11	31118
Thermosets	Phenol resin	Proprietary	1.55E-03	6.0	60000	3.11	31118
Other inorganic materials	Metal Hydroxide	Proprietary	3.86E-04	1.5	15000	0.78	7780
Other inorganic materials	Carbon black	1333-86-4	7.73E-05	0.3	3000	0.16	1556
Subtotal			2.58 E-02	100.00	1000000	51.86	518640

Leadframe

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Copper & its alloys	Copper	7440-50-8	1.94 E-02	97.50	975000	39.01	390133
Copper & its alloys	Iron	7439-89-6	4.67 E-04	2.35	23500	0.94	9403
Copper & its alloys	Zinc	7440-66-6	2.38 E-05	0.12	1200	0.05	480
Copper & its alloys	Phosphorus	7723-14-0	5.96 E-06	0.03	300	0.01	120
Subtotal			1.99 E-02	100.00	1000000	40.01	400136

Internal Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	1.99 E-05	100.0	1000000	0.04	401

External Leadframe Plating

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Tin & its alloys	Tin	7440-31-5	1.34 E-03	100.0	1000000	2.71	27059

Bond Wires

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Gold	7440-57-5	5.40 E-05	100.0	1000000	0.11	1086

Chip

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Other inorganic materials	Doped Silicon	7440-21-3	2.49 E-03	100.0	1000000	5.02	50217

Die Attach

Description	Substance	CAS#	Weight (g)	Homogeneous Material Level		Component Level	
				Percentage (%)	PPM	Percentage (%)	PPM
Precious metals	Silver	7440-22-4	8.97 E-05	73.40	734000	0.18	1806
Thermoset	Epoxy Resin	Proprietary	2.24 E-05	18.35	183500	0.05	451
Other organic materials	Metal oxide	Proprietary	3.36 E-06	2.75	27500	0.01	68
Other organic materials	Amine	Proprietary	3.36 E-06	2.75	27500	0.01	68
Other organic materials	Gamma Butyrolactone	Proprietary	3.36 E-06	2.75	27500	0.01	68
Subtotal			1.22 E-04	100.0	1000000	0.25	2460

Package Totals	Weight (g)	Percentage (%)	PPM
	4.97 E-02	100	1000000

Note: The information provided in this declaration are true to the best of ADI's knowledge
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